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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Mezenner

Art Unit: 2873

Serial No.: 10/749,277

Examiner: Dinh, Jack

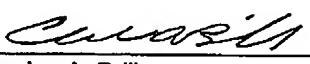
Filed: 31 December 2003

Docket No. TI-33824

For: VIA ADHESION IN MULTILAYER MEMS STRUCTURE

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| NAME OF INVENTOR(S): | |
| Mezenner | |
| TITLE OF INVENTION: | |
| VIA ADHESION IN MULTILAYER MEMS STRUCTURE | |
| TI FILE NO.: TI 22004 | DEPOSIT ACCT. NO.: 00 0000 |
| RECEIPT DATE & SERIAL NO.: | |
| Application No.: 10/749,277 | |
| Filing Date: 31 December 2003 | |